

PATENT ASSIGNMENT

SUBMISSION TYPE: NEW ASSIGNMENT**APPLICATION NUMBER**
10/248716**NATURE OF CONVEYANCE:** ASSIGNMENT OF ASSIGNOR'S INTEREST**CONVEYING PARTY DATA****Name:** Tong, Ho-Ming**Execution Date:** 10/29/2002**Name:** Lee, Chun-Chi**Execution Date:** 10/28/2002**Name:** Fang, Jen-Kuang**Execution Date:** 10/28/2002**Name:** Huang, Min-Lung**Execution Date:** 10/28/2002**Name:** Chen, Jau-Shoung**Execution Date:** 10/30/2002**Name:** Su, Ching-Huei**Execution Date:** 11/01/2002**Name:** Weng, Chao-Fu**Execution Date:** 10/29/2002**Name:** Chou, Yu-Chen**Execution Date:** 11/05/2002**Name:** Wu, Tsung-Hua**Execution Date:** 10/28/2002**Name:** Tao, Su**Execution Date:** 10/28/2002**RECEIVING PARTY DATA****Name:** Advanced Semiconductor Engineering, Inc.**Street Address:** 26, Chin 3rd Rd., Nantze Export Processing Zone**Internal Address:****City:** Kaohsiung**State:****Country:** TAIWAN**Postal Code:** 811**800005251****PATENT**
REEL: 013420 FRAME: 0751**OP \$40.00 10248716**

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CUSTOMER NUMBER: 031561

NAME OF PERSON SIGNING: Belinda Lee

DATE SIGNED: 02/12/2003

Total Attachments: 3

ASSIGNMENT

WHEREAS,

- | | |
|-------------------|-------------------|
| 1. Ho-Ming Tong | 2. Chun-Chi Lee |
| 3. Jen-Kuang Fang | 4. Min-Lung Huang |
| 5. Jau-Shou Chen | 6. Ching-Huei Su |
| 7. Chao-Fu Weng | 8. Yu-Chen Chou |
| 9. Tsung-Hua Wu | 10. Tao, Su |

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **BUMP FABRICATION PROCESS**

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, **Advanced Semiconductor Engineering, Inc.**
of **26, Chin 3rd Rd., 811, Nantze Export Processing Zone, Kaohsiung, Taiwan, R.O.C.**

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Ho-Ming Tong

Date: 10/29/02

Sole or First Joint Inventor: Ho-Ming Tong

Signature: Chu-Chi Lee

Date: 10/28/02

Second Joint Inventor(if any): Chun-Chi Lee

Signature: Jen-Kuang Fang

Date: 10/28/02

Third Joint Inventor(if any): Jen-Kuang Fang

Signature: Min-Lung Huang

Date: 10/28/02

Fourth Joint Inventor(if any): Min-Lung Huang

Signature: Jau-Shoung Chen

Date: 2002-10-30

Fifth Joint Inventor(if any): Jau-Shoung Chen

Signature: Ching-Huei Su

Date: 11/01/02

Sixth Joint Inventor(if any): Ching-Huei Su

Signature: Chao-Fu Weng

Date: 10/29/02

Seventh Joint Inventor(if any): Chao-Fu Weng

Signature: Yu-Chen Chou

Date: 11/05/02

Eighth Joint Inventor(if any): Yu-Chen Chou

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Tsung-Hua Wu

Date: 10/28/02

Ninth Joint Inventor(if any): Tsung-Hua Wu

Signature: Tao, Su

Date: 10/28 '02

Tenth Joint Inventor(if any): Tao , Su